



17th IEEE European Test Symposium

May 28th - June 1st , 2012

Annecy, France

<http://www.ieee-ets.org/>

Information for Prospective Supporters

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ETS'12 Industrial-Relations Chairs

2012 European Test Symposium Support Opportunity “At a Glance”

- ETS is the annual premier European event totally devoted to test and test-synthesis of micro-electronic circuits and systems, attracting around 200 industrial and academic professionals from around the world.
- ETS 2012 will be held in Annecy, France on May 28–June 1, 2012.
- Your company is invited to support ETS'12 at Bronze (€1500), Silver (€2500), Gold (€5000) or Platinum (€8000) level.
- The money will be used to reduce the cost of attendance, thereby attracting yet more attendees.
- In return: company logo on ETS web site, poster, and printed program; advertising space in the program booklet; advertisement e-mail to registered participants (support level Silver and up); display of company logos during session intervals; opportunity to provide company hand-out material; priority in the selection process for the Vendor Sessions; and more...
- Corporate supporters in 2008 - 2011: Advantest, Alter, ARM, Cadence Design Systems, Eles, Honeywell, Infineon Technologies, Intel, Mentor Graphics, NXP Semiconductors, OptimalTest, Pintail Technologies, Preciosa, Q-Star Test, Qualcomm, Spea, STC, STMicroelectronics, Synopsys, SynTest, Teradyne, TestAdvantage, TestInsight, Verigy, VSystems.
Now read on ...

About ETS'12

As you probably know, the IEEE European Test Symposium (ETS) is the largest European event completely devoted to testing micro-electronic circuits and systems. ETS is organized annually in a different European country. In 2012, ETS will be held in Annecy, France and will take place May 28 – June 1, 2012.

The ETS program comprises plenary keynotes, parallel paper sessions, vendor sessions, poster sessions, panel sessions, spring school, and fringe workshops. ETS is also renowned for its excellent Social Event and informal atmosphere, providing many opportunities for networking. ETS is annually attended by many design, design-for-test, and test professionals from companies and academia (attendance: ETS'07: 175+; ETS'08: 200+; ETS'09: 170+; ETS'10: 175+, ETS'11: 195).

To find out more about ETS'12, visit <http://ets2012.imag.fr/>.

Supporting ETS'12

Every year, ETS is supported by several companies. The support money is used to reduce the registration fees and hence make the event more accessible to all its attendees. In return, the supporting companies are allowed to make publicity in various ways. The corporate supporters in 2008-2011 were: Advantest, Alter, ARM, Cadence Design Systems, Eles, Honeywell, Infineon Technologies, Intel, Mentor Graphics, NXP Semiconductors, OptimalTest, Pintail Technologies, Preciosa, Q-Star Test, Qualcomm, Spea, STC, STMicroelectronics, Synopsys, SynTest, Teradyne, TestAdvantage, TestInsight, Verigy, and VSystems. We would like to invite your company to become a corporate supporter of ETS'12. Your presence at the symposium will give you an excellent opportunity to network with established and new design and test engineers.

Vendor Session Presentations

ETS'12 is also offering commercial vendors the opportunity to give technical presentations in a track parallel to the technical paper sessions. These presentations will be listed in the symposium program along with the technical sessions, and are targeted to the ETS technical audience. The Vendor Sessions differ from standard ETS presentations in that company names,

logos, and product names may be mentioned explicitly. Content could include product descriptions, case studies, best practices, and testimonials.

Presentation opportunities of 30-minutes duration are available: proposal selection is based the technical contact and relevance to the ETS'12 audience and topics. To find out more about the Vendor Sessions, visit the ETS'11 web site at <http://ets2012.imag.fr/> and follow the link to *Vendor Sessions, Call for Submissions*, or send an e-mail requesting more information. Please note: support of ETS'12 does not guarantee a presentation slot in the Vendor Session; we will do our utmost to accommodate your request for a slot but, in the end, we may be limited by the amount of time we have available for the sessions.

ETS'12 Support Grades

ETS has defined four different support grades (named Bronze, Silver, Gold, and Platinum), each with different support amounts and different publicity options. The full description of these four grades is below.

Bronze: At least €1500

- Supporter's name and logo will appear in the symposium's web page, the symposium posters, and the printed programs that will be distributed to the participants.
- *Half-page* advertising space in the program booklet for the event. The Advance Program will be available as a downloadable PDF document before the event, and the Final Program will be a hard-copy booklet handed out to all registered attendees.
- Priority in slot assignment for the Vendor Sessions.
- Constant exposure of company logo in a repeating presentation loop before, in-between, and after sessions.
- The supporter will be allowed to provide branded give-away items for inclusion in the symposium registration bag.

Silver: At least €2500

As per Bronze Level, plus:

- *Full-page* advertising space in the program booklet.
- The supporter's name and logo will appear in the Digest of Papers of the symposium.
- The supporter's name and logo will appear on the symposium's registration bag.
- Opportunity to send out *one* advertisement e-mail to registered symposium participants prior to the symposium.

Gold: At least €5000

As per Silver Level, plus:

- A special area at the symposium site will be assigned to the supporter as its own demonstration area (posters, leaflets, recruitment material, and other advertisement material). This could be a table (provided by ETS) or a booth (supplied by the corporate supporter).
- Opportunity to send out *two* advertisement e-mails to registered symposium participants prior to the symposium.

Platinum: At least €8000

This is a Main Corporate Supporter. As per Gold Level, plus:

- Guaranteed slot assignment in the Vendor Sessions.
- The support money will be used primarily for the Social Event of the workshop, which will be announced "to be offered by the Main Supporter(s)".
- Additional publicity paths can be arranged as requested by the supporter.

Next Steps

If your company is interested in taking advantage of this support opportunity, ETS'12 will draft a small contract, with the details of the deal and information regarding money transfer. Also, we will need a high-resolution electronic version of your company logo, as well as advertisement material for the program booklet.

Naturally, we would be happy to discuss with you any ideas you have to make this opportunity even more fruitful for your company.

We hope to hear from you soon.

Best regards,

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Affiliations of Past ETS Attendees

Advantest (Europe)
Advantest America
Agilent Technologies
Alter Technology Group Spain
AMD Corporation
Analog Devices
Aptina Imaging
ARM Ltd
ASICentrum s.r.o.
Atmel Norway & Rousset
Atrenta Inc
Auburn University
Azoteq
Bahcesehir University
Blue Pearl Software
Bordeaux 1 University
Brno University of Technology
Brown University
Cadence Design Systems
Catholic University - PUCRS
CEA Grenoble - LETI/DCIS/SCME
CEA LIST
Chiba University
Chinese Academy of Sciences
Chinese University of Hong Kong
Cisco Systems Inc
CNM - IMSE
Credence Systems (UK) Ltd
Credence Systems Corporation
CTU Prague
DAFCA
DeFacTo Technologies
Delft University of Technology
DMOS GmbH
Duke University
Electronic Systems & Software IET
ELES Semiconductor Equipment S.p.A.
ELMOS Semiconductor
EPSRC
Ericsson
ETH Zurich
European Patent Office
European University of Brest
Federal University of RGS - UFRGS
FEI STU
Focused Solutions Alliance
Fraunhofer IIS / EAS
Freescale Semiconductor
Georgia Institute of Technology
Graz University of Technology
Grenoble INP
Hiroshima City University
Huawei Technology Co Ltd
IBM
IHP GmbH
IM2NP
IMAG
IMEC
IMP GmbH
IMSE-CNM
INAOE
Indian Institute of Science Bangalore
Indian Institute of Technology Kharagpur
Infineon Technologies AG
Institute for Semiconductor Technology
Institute of Control Sciences RAM
Intel Corporation
Ippon Innovation
IROC Technologies
IST/INESC.ID
IXL Laboratory
JHU/Applied Physics Laboratory
Jozef Stefan Institute
KTH/ECS
Kuwait University
Kyushu Institute of Technology
Lancaster University
LCIS/INPG
Linköping University
LIRMM
LogicVision
Loughborough University
LSI Logic Corporation
LTX Corporation
MAGMA Design Corporation
McMaster University
Mechatronyx S.r.l.
Melexis
Mentor Graphics
NAIST Japan
NASA Goddard Space Flight Center
National Central University Taiwan
National Institute for Astrophysics
National Networked Tele Test Facility
National Technical University of Athens
National Tsing-Hua University Taiwan
National University of Defense Technology
NEC Labs
Newcastle University
Nokia Oyj
Norwegian Univ. of Science and Technology
Novas Software
NUDT
NXP Semiconductors
Optimal Test
Oxford University
Paderborn University
Philips Electronics
Philips Research
Pintail Technologies
Politecnico di Milano
Politecnico di Torino
Pontificia Universidad Catolica del Peru
Poznan University of Technology
PSA Peugeot Citroen
Purdue University
Qimonda AG
Q-Star Test
Qualcomm
Renesas Electronics Europe GmbH
Robert Bosch GmbH
Russia Academy of Science
Samsung Electronics
Schlumberger SRPC
SEMI Europe
Semtech Ltd
SFPengineering
Sharif University of Technology, Iran
Silesian University of Technology
Slovak Academy of Science
Slovak University of Technology
SPEA S.p.A.
STMicroelectronics
Synopsys Inc.
Tallinn University of Technology
Technical University of Catalonia
Technical University of Liberec
Technical University of Prague
Teradyne, Inc.
Test Advantage Inc
TestInsight Ltd.
Texas Instruments
Thales - Aerospace Division
Thomas Bata University
TIMA
TNO
Tokyo Metropolitan University
Tsinghua University
TU Berlin
UC San Diego
UFRGS – Univ. Federal do Rio Grande Sul
Universidade de Vigo
Universidade Federal de Pelotas
Universitat de les Illes Balears
Universitat Politècnica de Catalunya
Universität Freiburg
Universität Paderborn
University Carlos III de Madrid
University College Cork
University of Alabama
University of Algarve
University of Bologna
University of Bremen
University of Bristol
University of Cantabria
University of Edinburgh
University of Erlangen-Nürnberg
University of Freiburg
University of Hannover
University of Ioannina
University of Iowa
University of Limerick
University of Madrid
University of Manchester
University of Massachusetts Lowell
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University of Newcastle Upon Tyne
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University of Texas at Austin
University of Tokushima
University of Tokyo
University of Twente
University of Verona
University of Waterloo, Canada
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UPMC / LIP6 / ASIM
UTIA AV CR
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